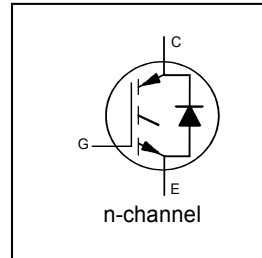


**INSULATED GATE BIPOLAR TRANSISTOR WITH ULTRAFAST SOFT RECOVERY DIODE**
**Features**

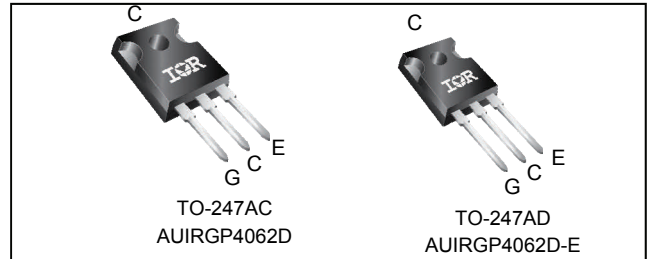
- Low  $V_{CE(on)}$  Trench IGBT Technology
- Low Switching Losses
- 5 $\mu$ s SCSOA
- Square RBSOA
- 100% of The Parts Tested for ILM<sup>①</sup>
- Positive  $V_{CE(on)}$  Temperature Coefficient.
- Ultra Fast Soft Recovery Co-pak Diode
- Tighter Distribution of Parameters
- Lead-Free, RoHS Compliant
- Automotive Qualified \*

**Benefits**

- High Efficiency in a Wide Range of Applications
- Suitable for a Wide Range of Switching Frequencies due to Low  $V_{CE(ON)}$  and Low Switching Losses
- Rugged Transient Performance for Increased Reliability
- Excellent Current Sharing in Parallel Operation
- Low EMI



$V_{CES} = 600V$   
 $I_C = 24A, T_C = 100^\circ C$   
 $t_{SC} \geq 5\mu s, T_{J(max)} = 175^\circ C$   
 $V_{CE(on)} \text{ typ.} = 1.60V$



G	C	E
Gate	Collector	Emitter

Base Part Number	Package Type	Standard Pack		Orderable Part Number
		Form	Quantity	
AUIRGP4062D	TO-247AC	Tube	25	AUIRGP4062D
AUIRGP4062D-E	TO-247AD	Tube	25	AUIRGP4062D-E

**Absolute Maximum Ratings**

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only; and functional operation of the device at these or any other condition beyond those indicated in the specifications is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability. The thermal resistance and power dissipation ratings are measured under board mounted and still air conditions. Ambient temperature ( $T_A$ ) is 25°C, unless otherwise specified.

	Parameter	Max.	Units
$V_{CES}$	Collector-to-Emitter Voltage	600	V
$I_C @ T_C = 25^\circ C$	Continuous Collector Current	48	A
$I_C @ T_C = 100^\circ C$	Continuous Collector Current	24	
$I_{CM}$	Pulse Collector Current $V_{GE} = 15V$	72	
$I_{LM}$	Clamped Inductive Load Current $V_{GE} = 20V$ <sup>①</sup>	96	
$I_F @ T_C = 25^\circ C$	Diode Continuous Forward Current	48	
$I_F @ T_C = 100^\circ C$	Diode Continuous Forward Current	24	
$I_{FSM}$	Maximum Repetitive Forward Current <sup>③</sup>	96	V
$V_{GE}$	Continuous Gate-to-Emitter Voltage	$\pm 20$	
	Transient Gate-to-Emitter Voltage	$\pm 30$	
$P_D @ T_C = 25^\circ C$	Maximum Power Dissipation	250	W
$P_D @ T_C = 100^\circ C$	Maximum Power Dissipation	125	
$T_J$ $T_{STG}$	Operating Junction and Storage Temperature Range	-55 to +175	°C
	Soldering Temperature, for 10 sec.	300 (0.063 in.(1.6mm) from case)	
	Mounting Torque, 6-32 or M3 Screw	10 lbf·in (1.1 N·m)	

**Thermal Resistance**

	Parameter	Min.	Typ.	Max.	Units
$R_{\theta JC}$ (IGBT)	Thermal Resistance Junction-to-Case (each IGBT) TO-247	—	—	0.65	°C/W
$R_{\theta JC}$ (Diode)	Thermal Resistance Junction-to-Case (each Diode) TO-247	—	—	1.62	
$R_{\theta CS}$	Thermal Resistance, Case-to-Sink (flat, greased surface) TO-247	—	0.24	—	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient (typical socket mount) TO-247	—	40	—	

\* Qualification standards can be found at [www.infineon.com](http://www.infineon.com)

**Electrical Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref.
V <sub>(BR)CES</sub>	Collector-to-Emitter Breakdown Voltage	600	—	—	V	V <sub>GE</sub> = 0V, I <sub>C</sub> = 100μA④	CT6
ΔV <sub>(BR)CES</sub> /ΔT <sub>J</sub>	Temperature Coeff. of Breakdown Voltage	—	0.30	—	V/°C	V <sub>GE</sub> = 0V, I <sub>C</sub> = 1mA (25°C-175°C)	
V <sub>CE(on)</sub>	Collector-to-Emitter Saturation Voltage	—	1.60	1.95	V	I <sub>C</sub> = 24A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 25°C	5,6,7
		—	2.03	—		I <sub>C</sub> = 24A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 150°C	9,10,11
		—	2.04	—		I <sub>C</sub> = 24A, V <sub>GE</sub> = 15V, T <sub>J</sub> = 175°C	
V <sub>GE(th)</sub>	Gate Threshold Voltage	4.0	—	6.5	V	I <sub>C</sub> = 700μA	9,10,
ΔV <sub>GE(th)</sub> /ΔT <sub>J</sub>	Threshold Voltage temp. coefficient	—	-18	—	mV/°C	V <sub>CE</sub> = V <sub>GE</sub> , I <sub>C</sub> = 1.0mA (25°C-175°C)	11,12
g <sub>fe</sub>	Forward Transconductance	—	17	—	S	V <sub>CE</sub> = 50V, I <sub>C</sub> = 24A, PW = 80μs	
I <sub>CES</sub>	Collector-to-Emitter Leakage Current	—	2.0	25	μA	V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V	
		—	775	—		V <sub>GE</sub> = 0V, V <sub>CE</sub> = 600V, T <sub>J</sub> = 175°C	
V <sub>FM</sub>	Diode Forward Voltage Drop	—	1.80	2.6	V	I <sub>F</sub> = 24A	8
		—	1.28	—		I <sub>F</sub> = 24A, T <sub>J</sub> = 175°C	
I <sub>GES</sub>	Gate-to-Emitter Leakage Current	—	—	±100	nA	V <sub>GE</sub> = ±20V, V <sub>CE</sub> = 0V	

**Switching Characteristics @ T<sub>J</sub> = 25°C (unless otherwise specified)**

	Parameter	Min.	Typ.	Max.	Units	Conditions	Ref. Fig.
Q <sub>g</sub>	Total Gate Charge (turn-on)	—	50	75	nC	I <sub>C</sub> = 24A V <sub>GE</sub> = 15V V <sub>CC</sub> = 400V	24
Q <sub>ge</sub>	Gate-to-Emitter Charge (turn-on)	—	13	20			CT1
Q <sub>gc</sub>	Gate-to-Collector Charge (turn-on)	—	21	31			
E <sub>on</sub>	Turn-On Switching Loss	—	115	201	μJ	I <sub>C</sub> = 24A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = +15V, T <sub>J</sub> = 25°C	CT4
E <sub>off</sub>	Turn-Off Switching Loss	—	600	700			
E <sub>total</sub>	Total Switching Loss	—	715	901			
t <sub>d(on)</sub>	Turn-On delay time	—	41	53	ns	R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH, Energy losses include tail & diode reverse recovery	CT4
t <sub>r</sub>	Rise time	—	22	31			
t <sub>d(off)</sub>	Turn-Off delay time	—	104	115			
t <sub>f</sub>	Fall time	—	29	41			
E <sub>on</sub>	Turn-On Switching Loss	—	420	—	μJ	I <sub>C</sub> = 24A, V <sub>CC</sub> = 400V, V <sub>GE</sub> = +15V, T <sub>J</sub> = 175°C ④	13,15, CT4 WF1,WF2
E <sub>off</sub>	Turn-Off Switching Loss	—	840	—			
E <sub>total</sub>	Total Switching Loss	—	1260	—			
t <sub>d(on)</sub>	Turn-On delay time	—	40	—	ns	R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH Energy losses include tail & diode reverse recovery	14,16 CT4 WF1 WF2
t <sub>r</sub>	Rise time	—	24	—			
t <sub>d(off)</sub>	Turn-Off delay time	—	125	—			
t <sub>f</sub>	Fall time	—	39	—			
C <sub>ies</sub>	Input Capacitance	—	1490	—	pF	V <sub>GE</sub> = 0V V <sub>CC</sub> = 30V f = 1.0Mhz	23
C <sub>oes</sub>	Output Capacitance	—	129	—			
C <sub>res</sub>	Reverse Transfer Capacitance	—	45	—			
RBSOA	Reverse Bias Safe Operating Area	FULL SQUARE				T <sub>J</sub> = 175°C, I <sub>C</sub> = 96A V <sub>CC</sub> = 480V, V <sub>p</sub> = 600V R <sub>g</sub> = 10Ω, V <sub>GE</sub> = +20V to 0V	4 CT2
SCSOA	Short Circuit Safe Operating Area	5	—	—	μs	V <sub>CC</sub> = 400V, V <sub>p</sub> = 600V R <sub>g</sub> = 10Ω, V <sub>GE</sub> = +15V to 0V	22,CT3 WF4
E <sub>rec</sub>	Reverse Recovery Energy of the Diode	—	624	—	μJ	T <sub>J</sub> = 175°C	17,18,19, 20,21
t <sub>rr</sub>	Diode Reverse Recovery Time	—	89	—	ns	V <sub>CC</sub> = 400V, I <sub>F</sub> = 24A, V <sub>GE</sub> = 15V,	
I <sub>rr</sub>	Peak Reverse Recovery Current	—	37	—	A	R <sub>G</sub> = 10Ω, L = 200μH, L <sub>S</sub> = 150nH	

**Notes:**

- ① V<sub>CC</sub> = 80% (V<sub>CES</sub>), V<sub>GE</sub> = 20V, L = 100μH, R<sub>G</sub> = 10Ω.
- ② This is only applied to TO-220AB package.
- ③ Pulse width limited by max. junction temperature.
- ④ Refer to AN-1086 for guidelines for measuring V<sub>(BR)CES</sub> safely.